

10G EPON OLT BOSA(10G1577T 10G1270R)

Description

- ◆ LD: 10G EML 7pin APD-TIA: 10G 6pin
- ◆ Mode of Fiber: SM
- ◆ Product structure note: SC/PC receptacle, Machining housing structure, receiver sealed with epoxy, with Isolator.

Absolute Maximum Ratings:

Parameter	Symbol	Min.	Max.	Unit
Storage Temperature	Tstg	-40	85	°C
Operating Temperature	Tcase	-5	75	°C
Soldering Temperature	Tsld	---	260<10s	°C
10G 1577nm EML Transmitter				
EML LD Reverse Voltage	V _{RL}	---	2	V
EML LD Forward Current	I _f	---	150	mA
EA Reverse Voltage	V _m	-3	1	V
EML MPD Reverse Voltage	V _{mon}	---	20	V
EML MPD Forward Current	I _{mon}	---	2	mA
TEC Cooling Voltage	V _{TEC}	---	1.45	V
TEC Cooling Current	I _{TEC}	---	0.8	A
10G 1270nm APD Receiver				
Storage Temperature	Tstg	-40	85	°C
Reverse Current	I _R	---	2	mA
ESD Susceptibility	ESD	---	150	V
Lead Soldering (Temperature)/(Time)	---	---	260/10	°C/Sec

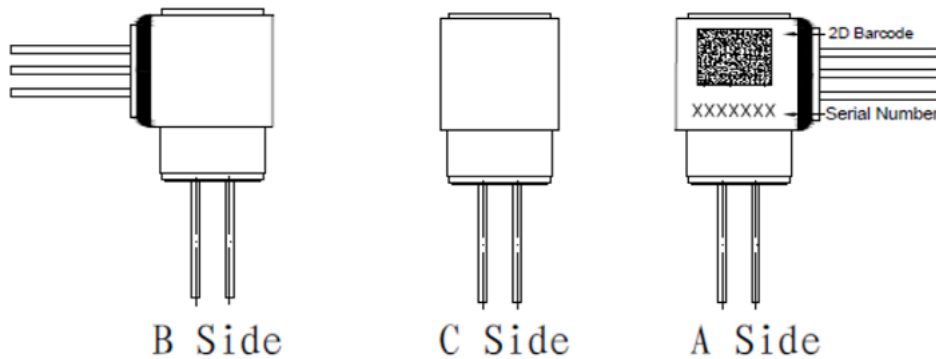
Electrical and Optical Characteristics – Transmitter:

Unless otherwise specified, the specifications below are defined at TC=25±3°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Note
Laser Operating Temperature	T _{ld}	---	45	---	°C	CW, I _{op} =I _{th} +20mA, T _c =25°C
Threshold Current	I _{th}	---	8	40	mA	at T _c =25°C
Operating Current	I _{op}	---	---	115	mA	at T _c =25°C P _f =6.8dBm
LD Forward Voltage	V _f	---	---	2.5	V	I _f =I _{op}
Center Wavelength	λ _c	1575	1577	1580	nm	CW, P _{op} =4ddBm, T _{ld}
Spectral Width(-20dB)	Δλ	---	0.2	0.4	nm	CW, P _{op} =4ddBm, T _{ld}
Side Mode Suppression Ratio	SMSR	35	---	---	dB	CW, P _{op} =4ddBm, T _{ld}

Marking Requirements

According to the Sunstar's Marking Requirements of Optical Active Devices ASSY.



The Inspection Requirements of End face

According to the International Standard of IPC8497-1.

Appearance and Packaging

According to the OSM's Specifications of Optical Active Devices Packaging Standard and Management.

Precaution:

- (1) The modules should be handled in the same manner as ordinary semiconductor devices to prevent the electro-static damages. For safe keeping and carrying, the modules should be packaged with ESD proof material. To assemble the modules on PCB, the workbench, the soldering iron and the human body should be grounded.
- (2) Please pay special attention to the atmosphere condition because the dew on the module may cause some electrical damages.
- (3) Under such a strong vibration environment as in automobile, the performance and reliability are not guaranteed.

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